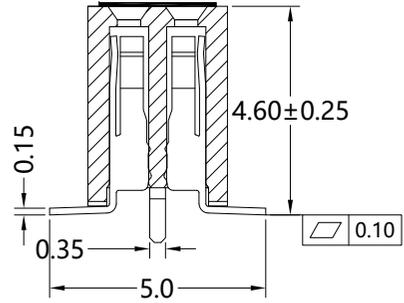
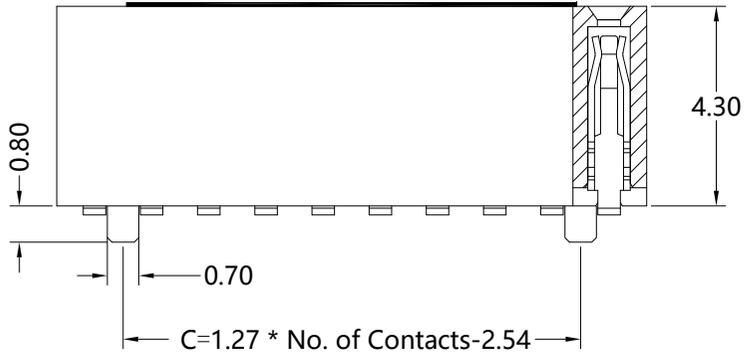
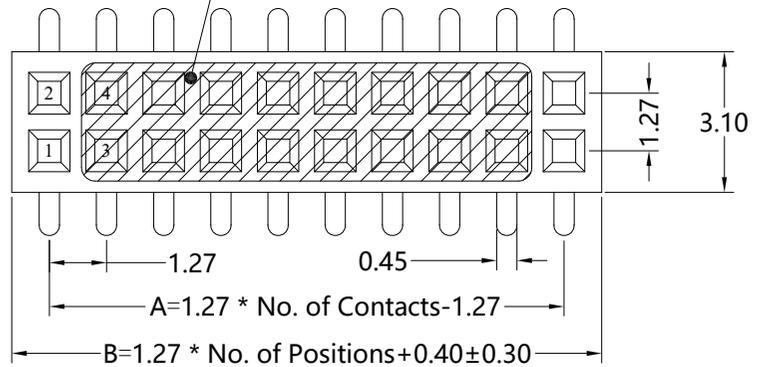


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2025/05/22	Wu Zonlin

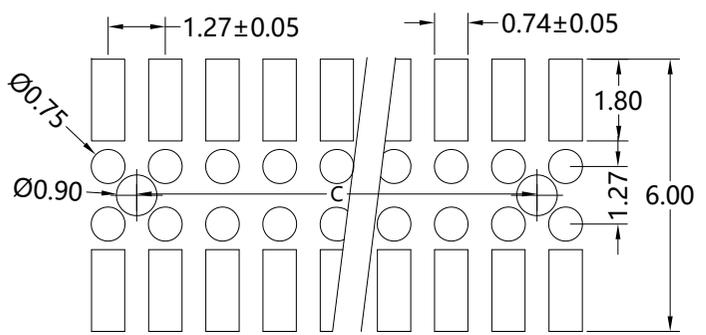
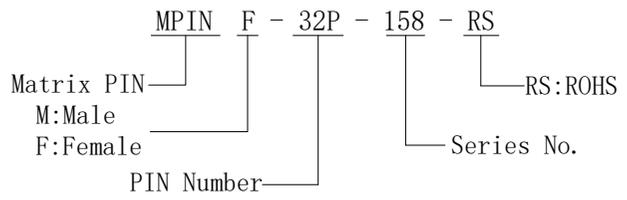
高温麦拉胶 :2*4~2*10P: 4.5*2.6mm
2*11~2*50P: 10.0*2.6mm



SPECIFICATIONS 规格

- CURRENT RATING 电流额定值 : 1AMP
- CONTACT RESISTANCE 接触电阻值 : 20mΩ Max
- INSULATION RESISTANCE 绝缘电阻值 : 1000MΩ Min
- DIELECTRIC WITHSTAND 耐压值 : 500V AC/minute
- OPERATION TEMPERATURE 工作温度 : -40°Cto+105°C
- CONTACT MATERIAL 端子材质 : Phosphor Bronze
- HOUSING MATERIAL 塑胶材质 :
- STANDARD 标准物料 : PA6T + 30%G.F. ; UL 94V-0;BLACK
- PLATING 电镀 : Au G/F Over 30u" Ni

MATRIX PART NO:



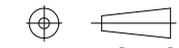
Recommended PCB Layout
(Tolerance: ±0.05)

No. of PIN/ROW	Dimension Information				
	A	B	26	31.75	33.42
02	1.27	2.94	27	33.02	34.69
03	2.54	4.21	28	34.29	35.96
04	3.81	5.48	29	35.56	37.23
05	5.08	6.75	30	36.83	38.50
06	6.35	8.02	31	38.10	39.77
07	7.62	9.29	32	39.37	41.04
08	8.89	10.56	33	40.64	42.31
09	10.16	11.83	34	41.91	43.58
10	11.43	13.10	35	43.18	44.85
11	12.70	14.37	36	44.45	46.12
12	13.97	15.64	37	45.72	47.39
13	15.24	16.91	38	46.99	48.66
14	16.51	18.18	39	48.26	49.93
15	17.78	19.45	40	49.53	51.20
16	19.05	20.72	41	50.80	52.47
17	20.32	21.99	42	52.07	53.74
18	21.59	23.26	43	53.34	55.01
19	22.86	24.53	44	54.61	56.28
20	24.13	25.80	45	55.88	57.55
21	25.40	27.07	46	57.15	58.82
22	26.67	28.34	47	58.42	60.09
23	27.94	29.61	48	59.69	61.36
24	29.21	30.88	49	60.96	62.63
25	30.48	32.15	50	62.23	63.90



Matrix Electronics Co.,Ltd

TOLERANCE:		DESIGN BY :	DATE :	PART NAME:	
X.X	±0.30	Wu Zonlin	2025/05/22	Pitch 1.27 mm H=4.60 mm SMT	
X.XX	±0.20	CHECKED BY:	DATE :	PART NO.	MPINF-32P-158-RS
		Hanson Huang	2025/05/22	MOLD NO.	NA
		APPROVED BY1:	DATE :	DRAW NO.	
		Richard Hsieh	2025/05/22	SHEET NO.	1 OF 1
		APPROVED BY2:	DATE :		
		Richard Hsieh	2025/05/22		



UNIT: mm [inch]
SCALE:1:1 SIZE:A4